IPC ASSOCIATION CONNE ELECTRONICS INDUS	© Copyright 2005. IPO	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					terials and N	Afg Ini	formation	1	
Supplier Info	rmation						·								
Company name*			Company uni	Company unique ID			Unique ID Authority					Response Date*			
nsemi											2025-0	2025-06-06			
Contact Name		Title - Contact			P	Phone - Contact*				Email	Email - Contact*				
Product-Env-Sto	ewards	Product Enviro Compliance			]	NA				Produ	Product-Env-Stewards@onsemi.com				
uthorized Repr	resentative*	Title - Representative			Phone - Representative*				Email	Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com				
Requ	ester Item Number	Mfr Item	em Number Mfr Item Name				Effective Dat	te Version	Version Manufa			Weig	ht*	UOM	Unit Type
		NCP115AMX330TCG 300 mA CMC			Low Dropout Regul	gulator 3V3   2025-06-06   PH		НМ		1.424		mg	Each		
Ianufacturii	ng Proccess Informati	on													
Termi	nal Plating / Grid Array Mate	Plating / Grid Array Material T		Terminal Base Alloy J		J-STD-020 MSL Rating		Peak Process Body Temperat		ire Max Time at Peak Temper		ature	ture Number of Reflow Cycles		eles
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		Au) (no	CU Alloy 1		1		260		С	30	seco		3		
Comments															
vel 1 - maximu	m time at peak temperatur	e during so	ldering is 10-30	0 seconds		·	·								
or more inform	ation regarding material c	omposition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a						
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of				
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted				
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the				

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	0.09	mg	Supplier	Silicon (Si)	7440-21-3		0.09	mg	
Die Attach	0.13	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.0416	mg	
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.0884	mg	
Lead Frame	0.58	mg	Supplier	Tin (Sn)	7440-31-5		0.0014	mg	
			Supplier	Zinc (Zn)	7440-66-6		0.0013	mg	
			Supplier	Chromium (Cr)	7440-47-3		0.0014	mg	
			Supplier	Copper (Cu)	7440-50-8		0.5758	mg	
Mold Compound-Black	0.6	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		0.048	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.003	mg	
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.012	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		0.519	mg	
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.018	mg	
Plating	0.004	mg	Supplier	Palladium (Pd)	7440-05-3		0.0001	mg	
			В	Nickel (Ni)	7440-02-0		0.0035	mg	
			Supplier	Gold (Au)	7440-57-5		0.0004	mg	
Wire Bond	0.02	mg	Supplier	Palladium (Pd)	7440-05-3		0.0002	mg	
			Supplier	Copper (Cu)	7440-50-8		0.0198	mg	